



#### 0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

## Product Summary (@TA = +25°C)

V <sub>RRM</sub> (V)	I <sub>O</sub> (A)	V <sub>F</sub> (V)	I <sub>R</sub> (μA)
1000	0.8	1.1	5

#### **Features and Benefits**

- Glass Passivated Die Construction
- Miniature Package Saves Space on PC Boards
- Reliable Robust Construction
- Ideal for SMT Manufacturing
- Low Forward Voltage Drop
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Description and Applications**

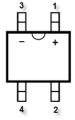
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

#### **Mechanical Data**

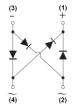
- Case: MBF
- Case Material: Molded Plastic.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity: As Marked on Body
- Weight: 0.08 grams (Approximate)







Pin Diagram



Internal Schematic

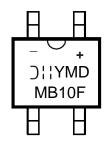
### **Ordering Information** (Note 4)

Part Number	Compliance	Case	Packaging
MB10F-13	Commercial	MBF	5,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



MB10F= Product Type Marking Code

Oli = Manufacturers' Code Marking

YMD = Date Code Marking

Y = Last Digit of Year (ex: 7 = 2017)

M = See Month/Code Table Below

D = Day 1~9 =1~9; Day 10~31= A~V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		1,000	<b>V</b>
RMS Reverse Voltage	V <sub>R(RMS)</sub>	700	V
Average Rectified Output Current (Note 5) @ $T_A = +125^{\circ}$ @ $T_A = +110^{\circ}$		0.5 0.8	Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	30	А
I <sup>2</sup> t Rating for Fusing (1ms < t < 8.3ms)	l <sup>2</sup> t	3.74	A <sup>2</sup> S

# **Thermal Characteristics**

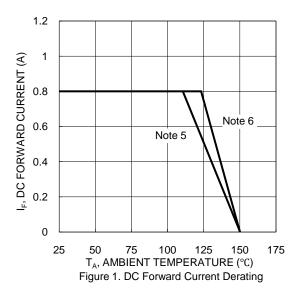
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 6) (Per Element)	R <sub>θJA</sub>	63	°C/W
Typical Thermal Resistance, Junction to Lead (Per Element)	R <sub>0</sub> JL	39	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

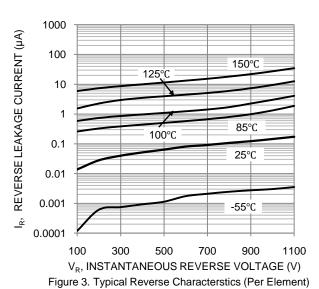
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	1,000	_	_	V	$I_R = 5\mu A$
Forward Voltage (Per Element)	VF	_	0.94	1.1	V	$I_F = 0.8A, T_A = +25^{\circ}C$
Leakage Current (Note 7) (Per Element)	I <sub>R</sub>		0.2 14	5 500	μA	V <sub>R</sub> = 1,000V, T <sub>A</sub> = +25°C V <sub>R</sub> = 1,000V, T <sub>A</sub> = +125°C
Total Capacitance (Per Element)	C <sub>T</sub>		8	_	pF	$V_R = 4V$ , $f = 1.0MHz$

- 5. Device mounted on FR-4 substrate, 1"\*1", 2oz, single-sided, PC boards with 0.1"\*0.15" copper pad.
  6. Device mounted on FR-4 substrate, 1"\*1", 2oz, single-sided, PC boards with 0.56"\*0.73" copper pad.
  7. Short duration pulse test used to minimize self-heating effect.







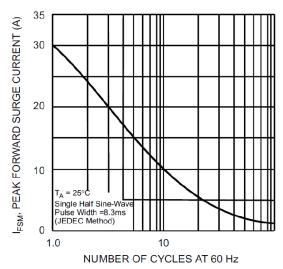
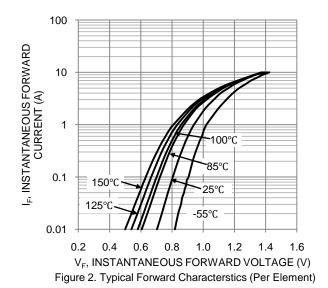
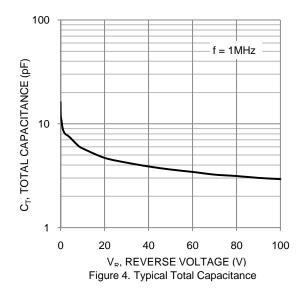


Figure 5. Maximum Peak Forward Surge Current (Per Leg)





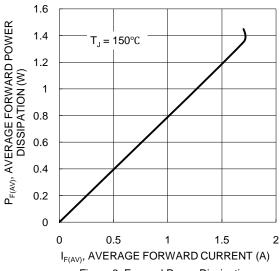
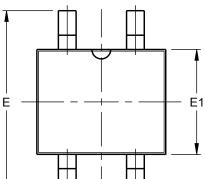


Figure 6. Forward Power Dissipation

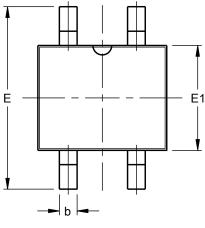


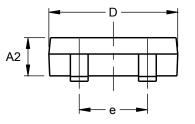
## **Package Outline Dimensions**

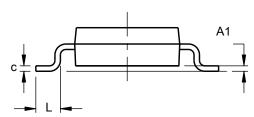
Please see http://www.diodes.com/package-outlines.html for the latest version.









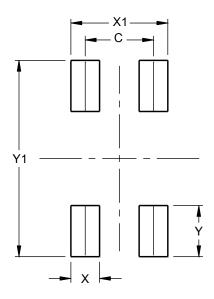


MBF						
Dim	Min	Max	Тур			
A1		0.20				
A2	1.20	1.60				
b	0.50	0.80				
С	0.15	0.35				
D	4.50	4.95				
Е	6.40	7.00				
E1	3.60	4.10				
е	2.30	2.70				
Ĺ	0.70	1.10				
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

MBF



Dimensions	Value
Dilliensions	(in mm)
С	2.50
Х	1.050
X1	3.55
Υ	1.875
Y1	7.20



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